

# IEC 60068-2-69 Ed. 1.0 b:1995, Environmental testing - Part 2: Tests - Test Te: Solderability testing of electronic components for surface mount technology by the wetting balance method



Describes two wetting balance methods. These methods determine quantitatively the solderability of terminations on surface mounted devices. The procedures describe the solder bath wetting balance method and the solder globuwetting balance method and are both applicable to components with metallic termination and metallized solder pads.

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